L Number	Hits	Search Text	DB	Time stamp
66	0	(29/619).ccls. and (chip adj resistor) and	USPAT;	2003/06/05 15:03
		multilayer	US-PGPUB;	
			IBM_TDB	
67	17		USPAT;	2003/06/05 15:05
		substrate and ((etch or etched or etching)	US-PGPUB;	
CO	1.5	with foil) and resistor	IBM_TDB	2002/06/05 15:00
68	15		USPAT; . US-PGPUB;	2003/06/05 15:08
		and ((etch or etched or etching) with foil) and resistor	IBM TDB	
69	31	(174/260).ccls. and substrate and ((etch	USPAT;	2003/06/05 15:08
09	31	or etched or etching) with foil) and	US-PGPUB;	2003/00/03 13.08
		resistor	IBM TDB	
70	19		USPAT;	2003/06/05 15:09
, ,		or etched or etching) with foil) and	US-PGPUB;	2000,00,00 10.03
		resistor and multilayer\$3	IBM TDB	
_	608	29/611.ccls.	USPĀT;	2003/06/04 19:12
			US-PGPUB;	
			IBM TDB	
-	586	29/\$.ccls. and substrate and ((etch or	USPĀT;	2003/06/04 15:56
		etched or etching) with foil)	US-PGPUB;	!
		-	IBM_TDB	
-	0	29/\$.ccls. and (photoresistive with	USPAT;	2003/06/04 15:56
		substrate) and ((etch or etched or	US-PGPUB;	
		etching) with foil)	IBM_TDB	
-	4	29/\$.ccls. and (photoresistive and	USPAT;	2003/06/04 15:57
		substrate) and ((etch or etched or	US-PGPUB;	
		etching) with foil)	IBM_TDB	0000/06/04 36 00
-	11		USPAT;	2003/06/04 16:03
į		layer or coat or coating)) and substrate	US-PGPUB;	
		and ((etch or etched or etching) with	IBM_TDB	
_	17	foil) 29/\$.ccls. and (resistive adj (film or	USPAT;	2003/06/04 16:11
_	Ι,	layer or coat or coating)) and substrate	US-PGPUB;	2003/00/04 10.11
		and ((etch or etched or etching) and foil)	IBM TDB	
_	100	resistor and (resistive adj (film or layer	USPAT;	2003/06/04 16:12
	100	or coat or coating)) and substrate and	US-PGPUB;	2003/00/04 10:12
		((etch or etched or etching) and foil)	IBM TDB	
_	48	((method or process) with resistor) and	USPAT;	2003/06/04 19:49
		(resistive adj (film or layer or coat or	US-PGPUB;	
		coating)) and substrate and ((etch or	IBM TDB	
		etched or etching) and foil)	_	
-	7	(, , , , , , , , , , , , , , , , , , ,	USPAT	2003/06/04 16:19
		"5872038" "5935642" "5960270"		
ŀ		"5994997").PN.		
-	8	("4479890" "4610810" "4870746"	USPAT	2003/06/04 16:30
		"5162144" "5260170" "5338567"		
	20	"5347258" "5792594").PN.	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	2002/06/04 16 12
-	28	((method or process) with resistor) and	USPAT;	2003/06/04 16:42
		(resistive adj (film or layer or coat or coating)) and substrate and (etch or	US-PGPUB;	
		etched or etching) and foil and width	IBM_TDB	
_	28		USPAT;	2003/06/04 16:43
	20	(resistive adj (film or layer or coat or	US-PGPUB;	2000,00,04 10.45
		coating)) and substrate and (etch or	IBM TDB	
		etched or etching) and foil with (thick or		
1		thickness or width)		
_	28		USPAT;	2003/06/04 16:48
	20	(resistive adj (film or layer or coat or	US-PGPUB;	
		coating)) and substrate and (etch or	IBM TDB	
		etched or etching) and (foil with (thick		
		or thickness or width))		•
_	32		USPAT;	2003/06/04 19:42
		(resistive adj (film or layer or coat or	US-PGPUB;	
		coating)) and substrate and ((etch or etched or etching or polishing) with foil)	IBM_TDB	

-	17	("2945180" "3808576" "3813631"	USPAT	2003/06/04 17:03
		"4174513" "4737747" "4888574"		
		"4892776" "5336391" "5422313"		
		"5483217" "5756971" "5864281"		
		"5907273" "5994997" "6141870" "6232042" "6248612").PN.		
	14	1	USPAT;	2003/06/05 09:15
_	14	((etch or etched or etching) with foil)	US-PGPUB;	2003/06/05 09:13
		and resistor	IBM TDB	
_	38	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05 09:16
_	1	((etch or etched or etching) with foil)	US-PGPUB;	2003/00/03 03.10
		and resistor	IBM TDB	
_	3	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05 09:18
		((etch or etched or etching) with foil)	US-PGPUB;	
		and ((method or processor assembling or	IBM TDB	
		making or manufacturing or step) adj	-	
		resistor)		1
-	79	• • •	USPAT;	2003/06/05 09:19
		((etch or etched or etching) with foil)	US-PGPUB;	
			IBM_TDB	
-	13		USPAT;	2003/06/05 09:19
		((etch or etched or etching) with foil)	US-PGPUB;	
	,	and resistor	IBM_TDB	2002/06/05 00:00
-	1	(438/462,977).ccls. and substrate and	USPAT; US-PGPUB;	2003/06/05 09:20
		(etch or etched or etching) and foil and resistor	IBM TDB	
_	18		USPAT	2003/06/05 10:42
_	1 10	6232042.URPN.	USPAT	2003/06/05 10:42
_	1	6194990.pn.	USPAT;	2003/06/05 10:40
	_	0134330.pm	US-PGPUB;	2003,00,03 11.20
			IBM TDB	
_	11	("3719508" "4786564" "4888574"	USPAT	2003/06/05 10:48
		"4892776" "5053318" "5336391"		
		"5347258" "5403672" "5560812"		
		"5679498" "6171921").PN.		
-	11	4297670.URPN.	USPAT	2003/06/05 10:50
-	12	("2945180" "3808576" "3813631"	USPAT	2003/06/05 10:51
		"4174513" "4888574" "4892776"		
		"5336391" "5422313" "5483217"		
	,	"5756971" "5864281" "5907273").PN.	HCDAM	2003/06/05 10:52
1 _	3 11	laminated adj resistor	USPAT USPAT:	2003/06/05 10:32
-	1	laminated adj lesistor	US-PGPUB;	2003/00/03 11.21
			IBM TDB	
-	1988	chip adj resistor	USPAT;	2003/06/05 11:30
1		,	US-PGPUB;	-:
			IBM TDB	
-	570	(chip adj resistor) and glass	USPAT;	2003/06/05 11:22
	1	· · · · · · · · · · · · · · · · · · ·	US-PGPUB;	
			IBM_TDB	
-	328	(chip adj resistor) and glass and terminal	USPĀT;	2003/06/05 11:22
1			US-PGPUB;	
			IBM_TDB	0000/06/05 11 55
-	126	(chip adj resistor) and glass and terminal	USPAT;	2003/06/05 11:23
		and nickel	US-PGPUB;	
	126	(method or process or manufacturing or	IBM_TDB USPAT;	2003/06/05 11:24
-	120	making or producing or steps) and (chip	US-PGPUB;	2003/00/03 11:24
		adj resistor) and glass and terminal and	IBM TDB	
	1	nickel	1511_155	
-	11	(method or process or manufacturing or	USPAT;	2003/06/05 11:24
		making or producing or steps) adj (chip	US-PGPUB;	
		adj resistor) and glass and terminal and	IBM_TDB	
		nickel	_	
-	5	("3167451" "4437140" "4684916"	USPAT	2003/06/05 11:28
		"5510594" "5680092").PN.		
-	30	(29/610.1,620,621).ccls. and (chip adj	USPAT;	2003/06/05 11:39
		resistor)	US-PGPUB;	
			IBM_TDB	000000000000000000000000000000000000000
-	10	4267634.URPN.	USPĀT	2003/06/05 11:36

	5	(29/610.1,620,621).ccls. and (chip adj	USPAT;	2003/06/05 11:40
_	3		US-PGPUB;	2003/06/05 11:40
		resistor) and multilayer		
	1.1	(220/200 200 220)	IBM_TDB	0000 /06 /05 11 41
_	11		USPAT;	2003/06/05 11:41
		resistor) and multilayer	US-PGPUB;	
			IBM_TDB	
-	13		USPAT	2003/06/05 11:42
_	10		USPAT	2003/06/05 11:47
-	1	4267634.pn. and glass	USPAT;	2003/06/05 13:32
			US-PGPUB;	
			IBM_TDB	
_	10	4267634.URPN.	USPAT	2003/06/05 13:12
_	0	multilayered adj resistor	USPAT;	2003/06/05 13:16
		_	US-PGPUB;	
			IBM TDB	
_	8	multi-layered near resistor	USPĀT;	2003/06/05 13:20
			US-PGPUB;	
			IBM TDB	
_	32723	ceramic near glass	USPAT;	2003/06/05 13:20
	32,23	Columno mout grade	US-PGPUB;	2003,00,00 13:20
			IBM TDB	
	3649	(ceramic near glass) and resistor	USPAT;	2003/06/05 13:21
_	3049	(ceramic hear grass) and resistor	US-PGPUB;	2003/00/03 13.21
			IBM TDB	
	81	(ceramic near glass) and (chip adj	USPAT;	2003/06/05 13:21
_	0.1	resistor)	US-PGPUB;	2003/06/03 13:21
		resistory		
		4067624	IBM_TDB USPAT;	2003/06/05 13:36
_	0	4267634.pn. and nickel		2003/06/05 13:36
			US-PGPUB;	
	2.51.0		IBM_TDB	0000 (06 (05 10 07
-	3612	nickel with melting	USPAT;	2003/06/05 13:37
			US-PGPUB;	
			IBM_TDB	
-	2226	nickel with (melting adj (point or	USPAT;	2003/06/05 13:38
		temperature))	US-PGPUB;	
			IBM_TDB	
-	314		USPAT;	2003/06/05 13:39
		temperature))	US-PGPUB;	
			IBM TDB	
-	17	nickel near (melting adj (point or	USPAT;	2003/06/05 13:50
	1	temperature)) and resistor	US-PGPUB;	
			IBM TDB	
_	9	palladium near (melting adj (point or	USPAT;	2003/06/05 13:51
		temperature)) and resistor	US-PGPUB;	
			IBM TDB	